

CP-800S, CP-1000S

~Copper paste for through-hole~

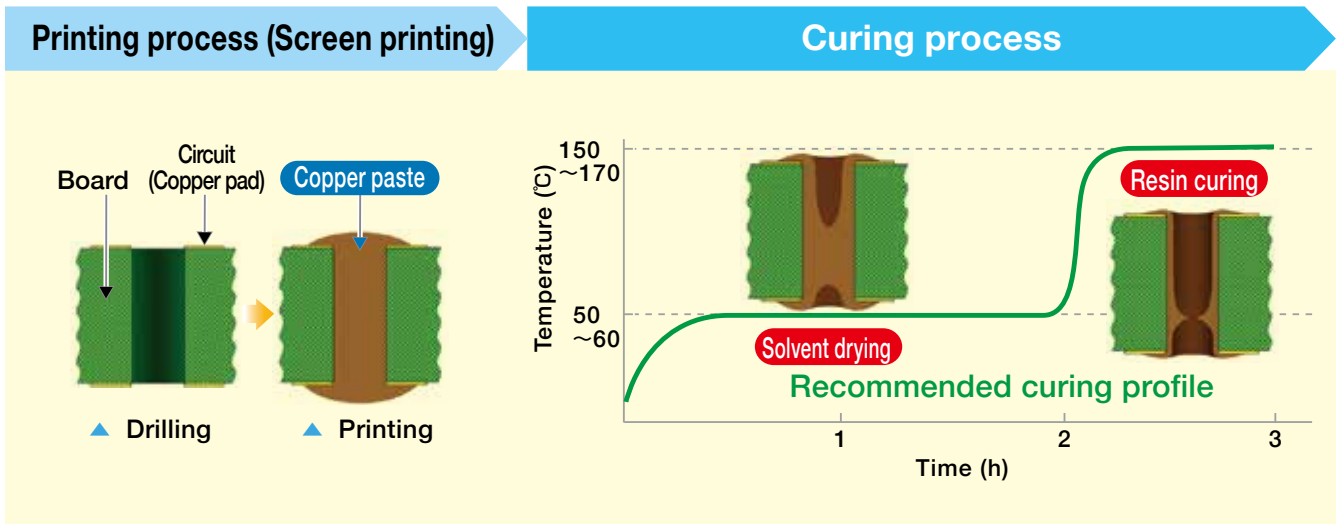
Highly-reliable copper paste for through-hole, available for automotive boards.

Features

- Compared to copper plating or silver paste, copper paste can reduce production cost.
- Available for small diameter through-hole and four-layer boards.
- Meets all the industrial standards of reliability evaluations required by electrical assembly field. Excellent electromigration resistance and available for wide range of board types, from for consumer to automobile.

Printing and Curing process

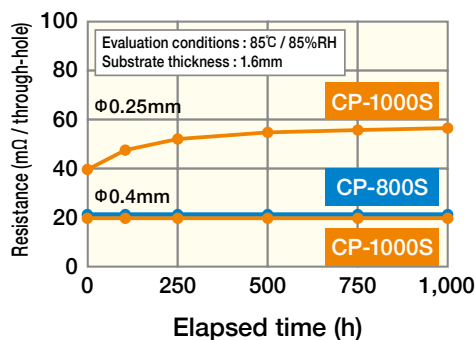
- Compared to plating, copper paste printing process is simpler and produces less waste.
- Available for substrates of various thickness and hole size.



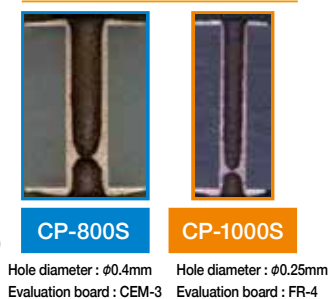
Application examples for small diameter through-hole and four-layer boards

- CP-800S used in various fields maintains high reliability even in the case of small diameter and four-layer boards.
- We offer CP-1000S(developed product) applicable for $\Phi 0.25\text{mm}$ diameter through-hole with 1.6mm substrate thickness.

● Small diameter through-hole



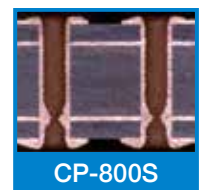
Cross-section of through-hole



● Four-layer board

Cross-section of four-layer board

Hole diameter (mm)	0.3	
Substrate thickness (mm)	1.0	
Copper foil thickness (μm)	L1	35
	L2	35
	L3	35
	L4	35
Prepreg material thickness (mm)	0.13	
Core material thickness (mm)	0.7	



Resistance : 15m Ω / through-hole*
*Not guaranteed value